

FIG. 1

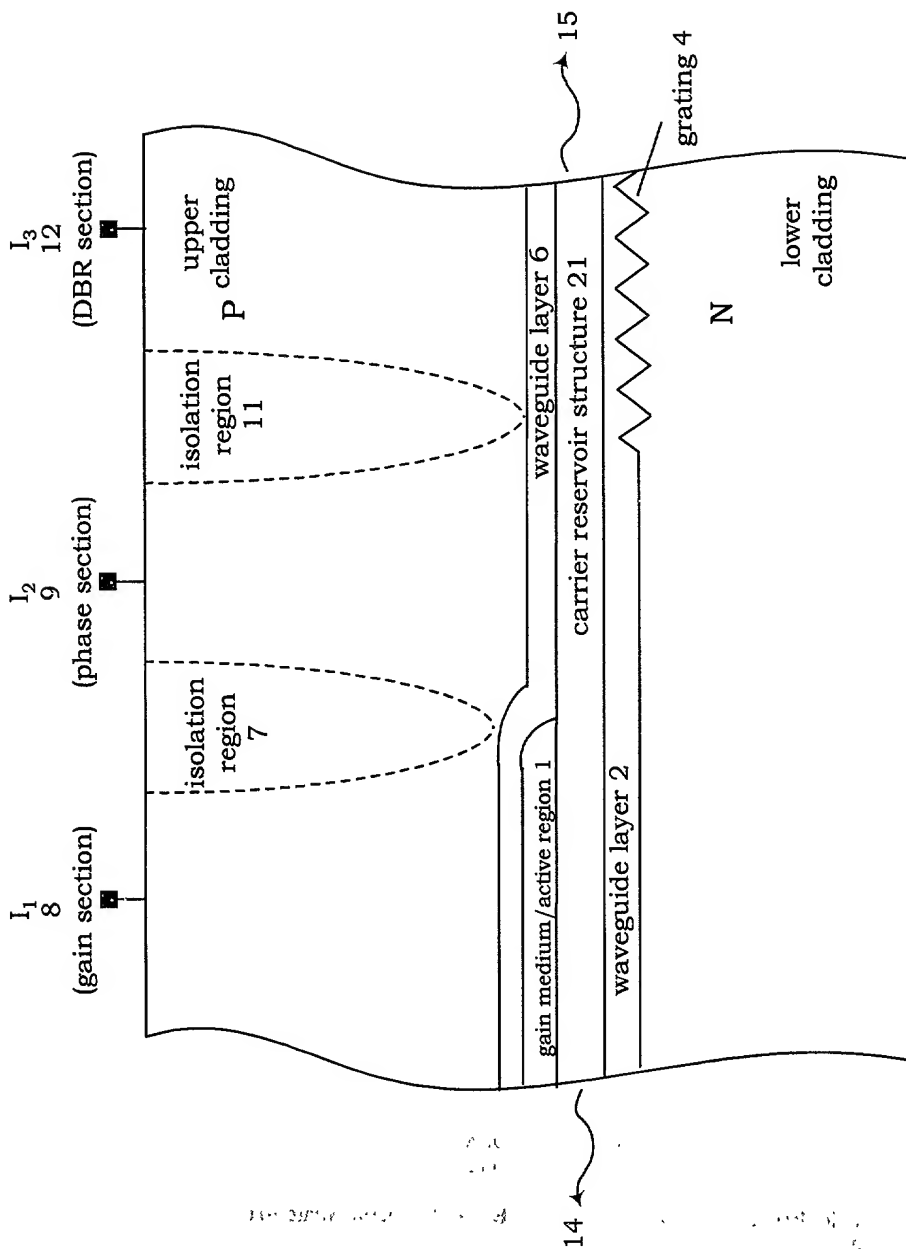


FIG. 2

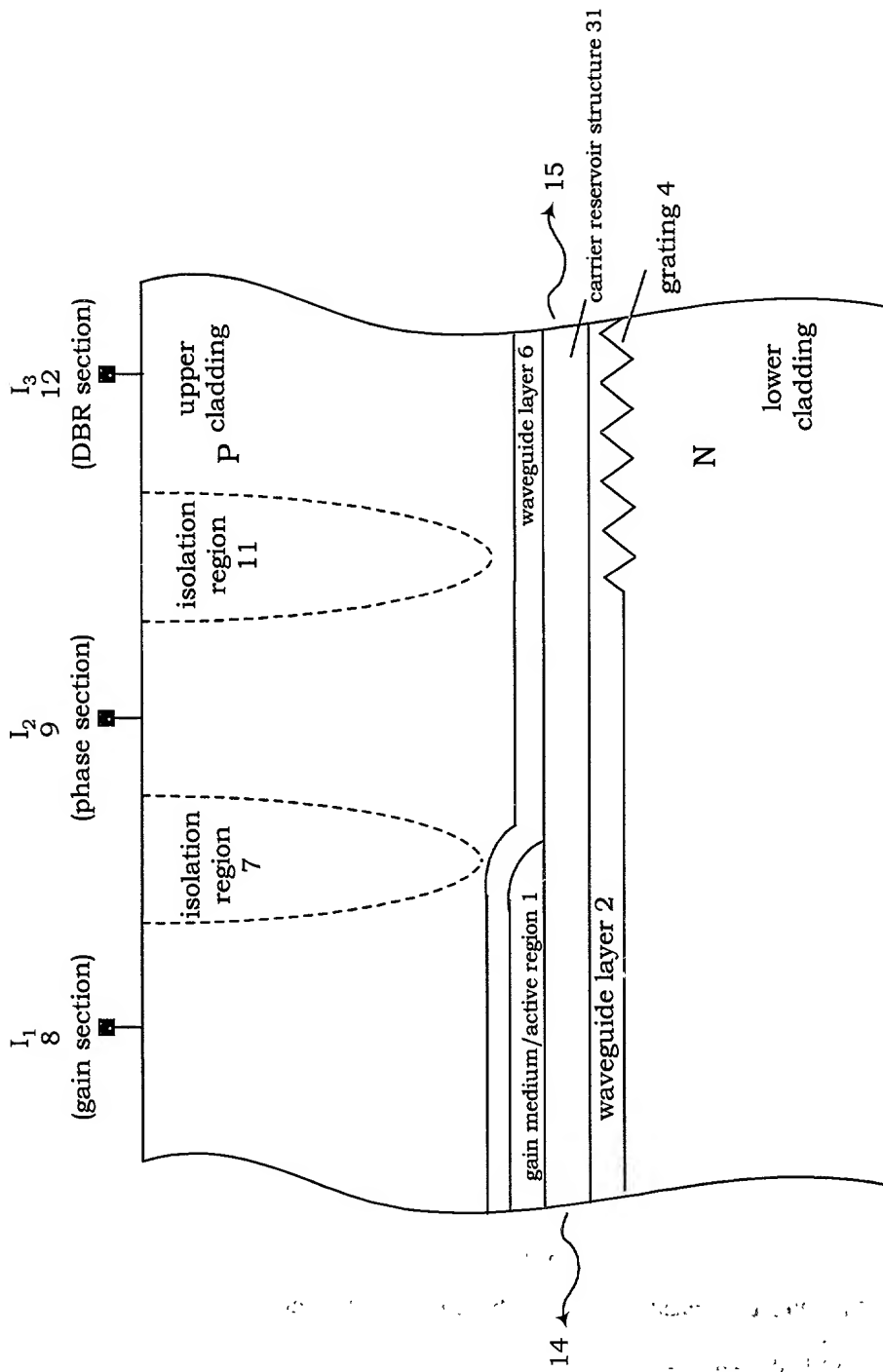


FIG. 3

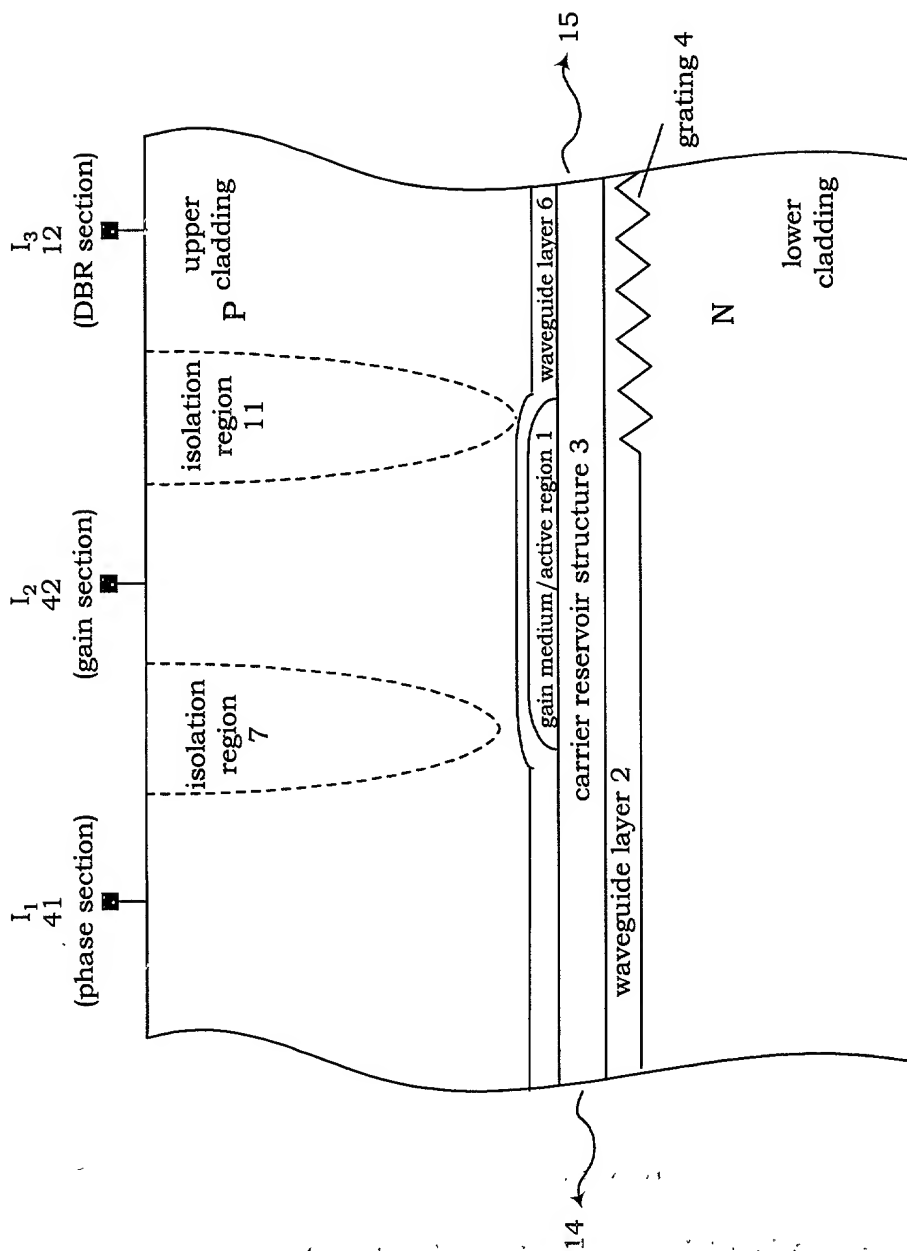


FIG. 4

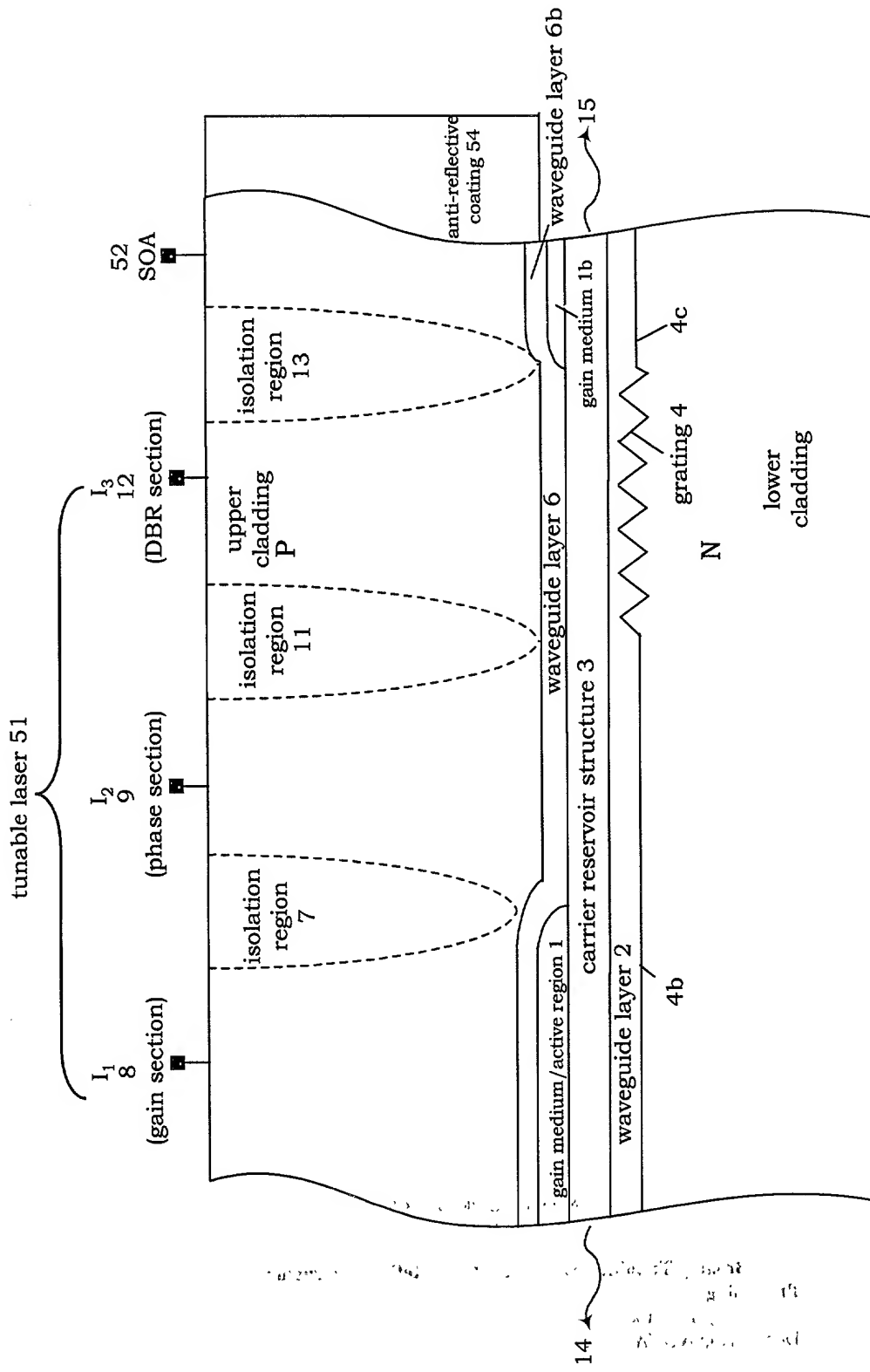
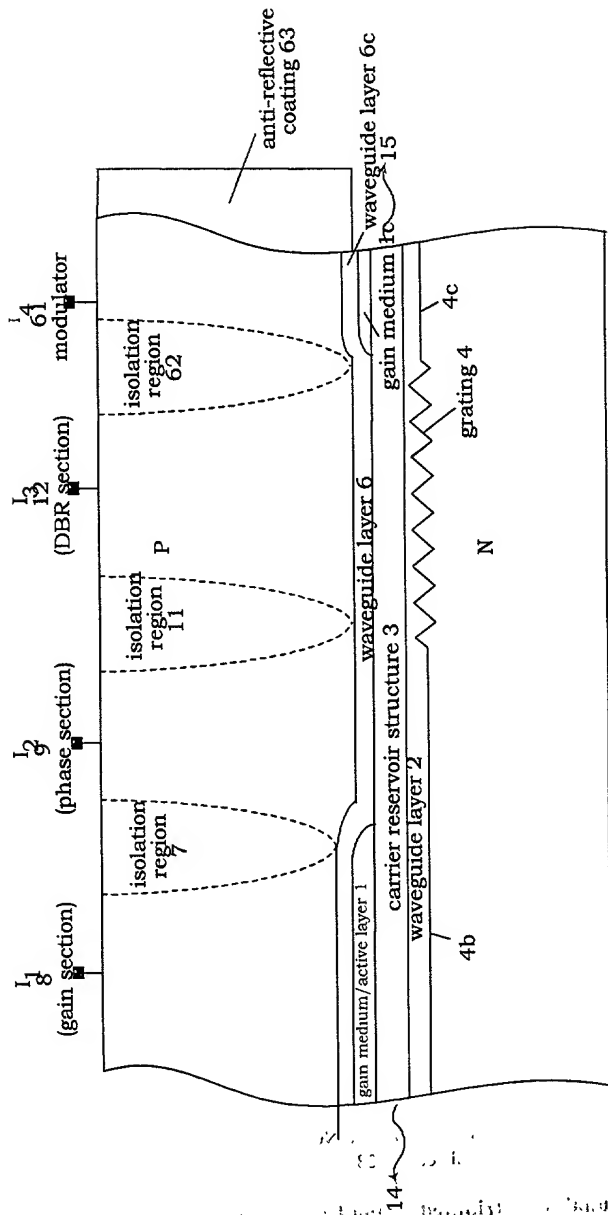


FIG. 5



60

FIG. 6

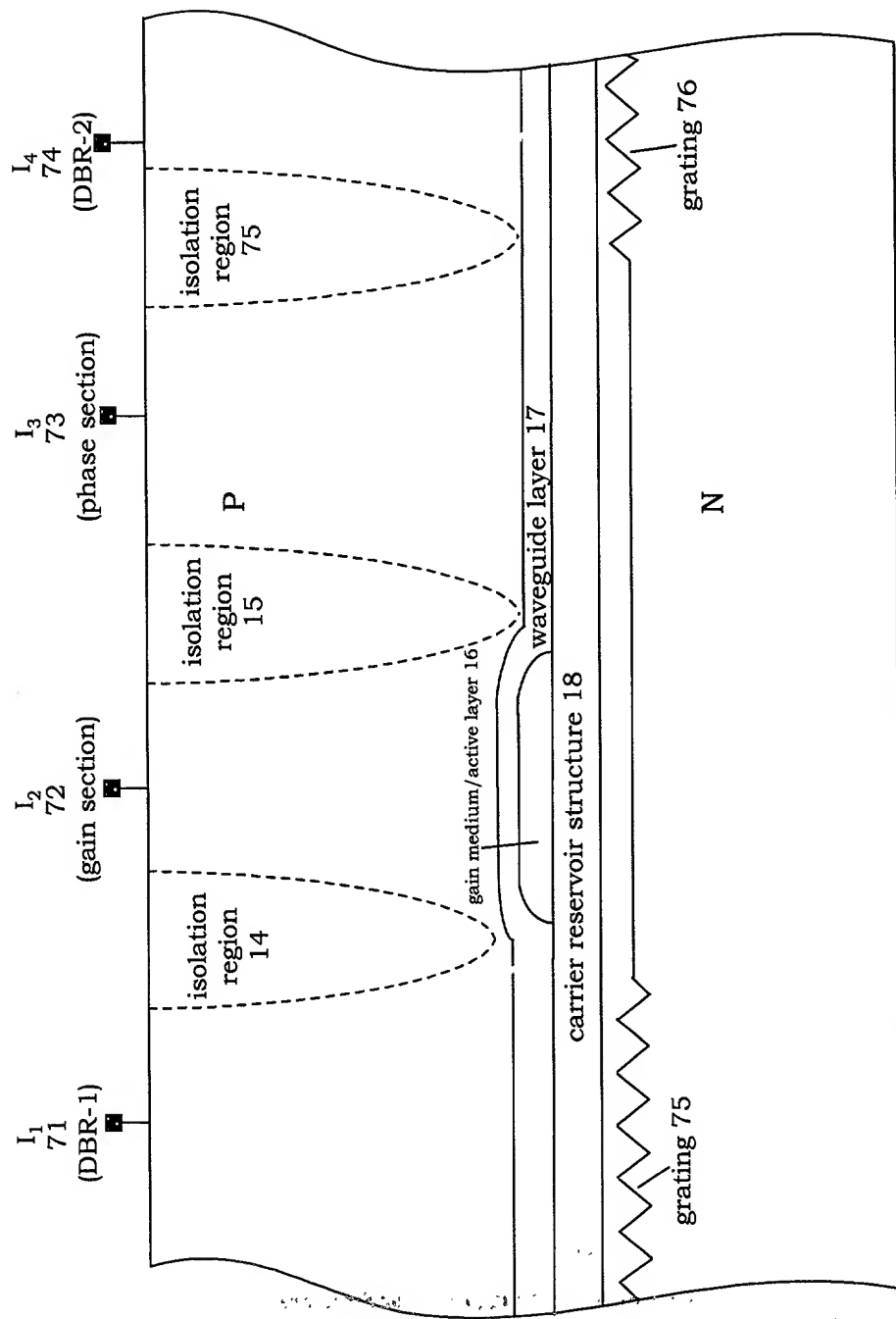
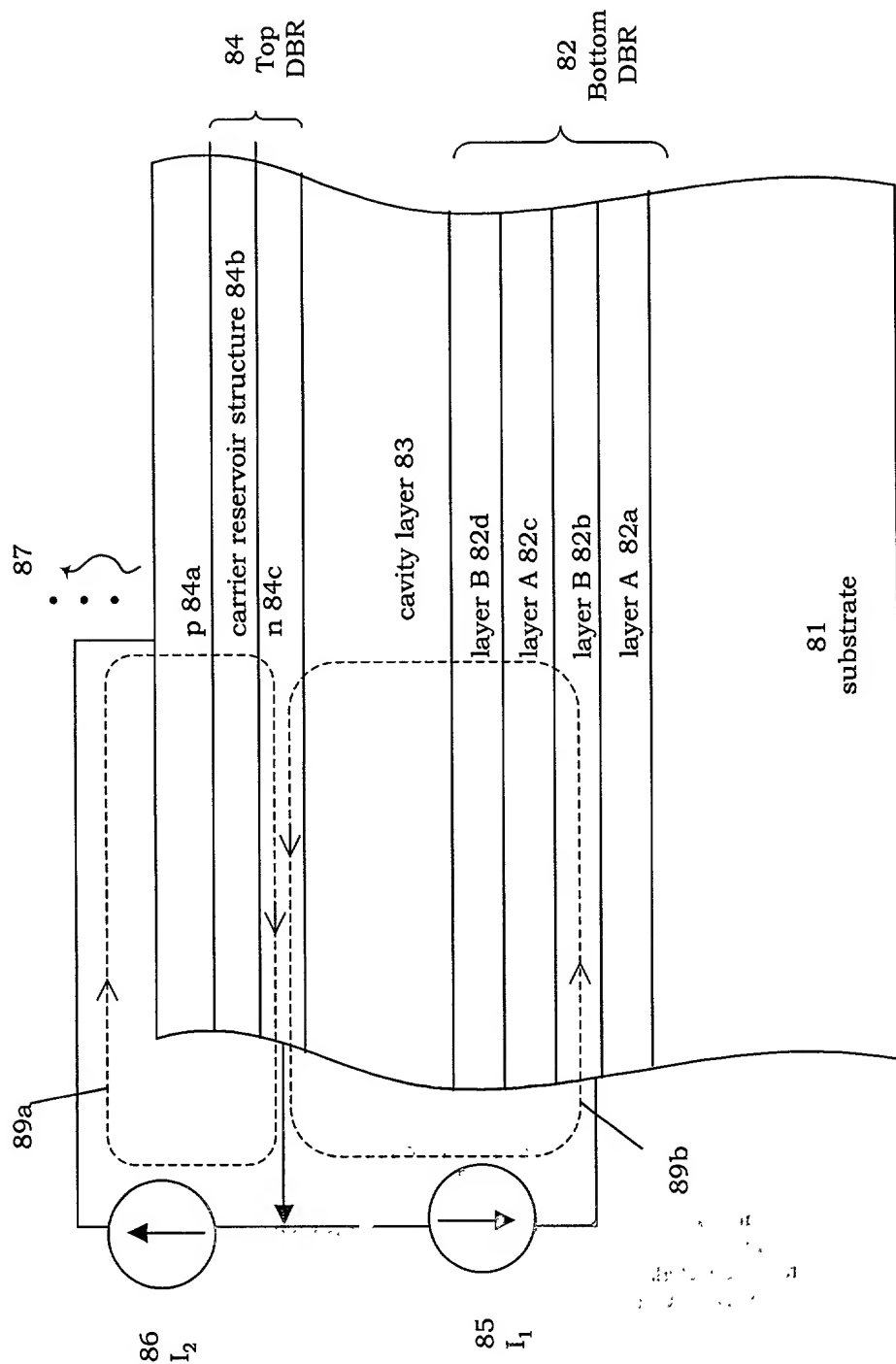
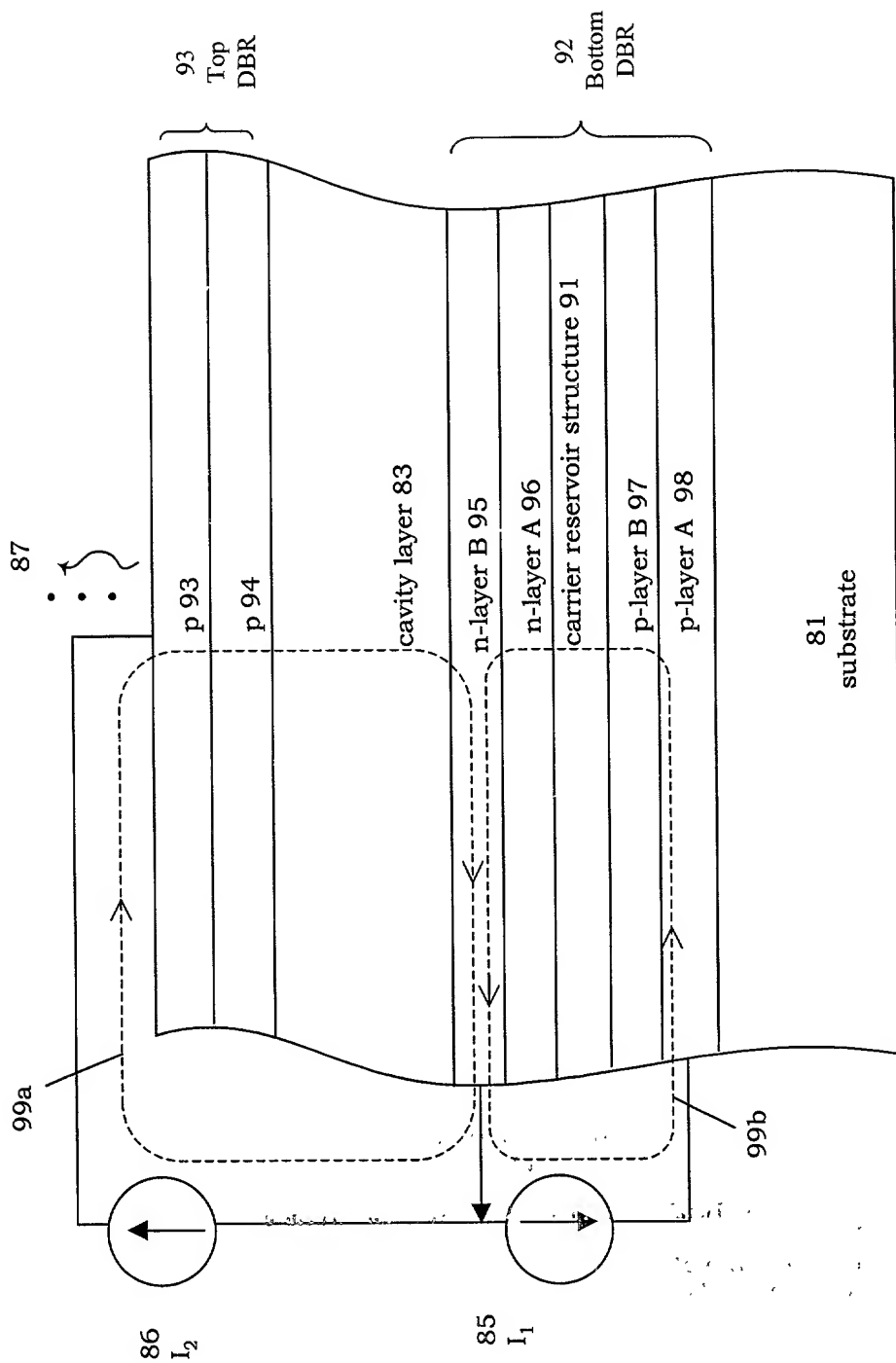
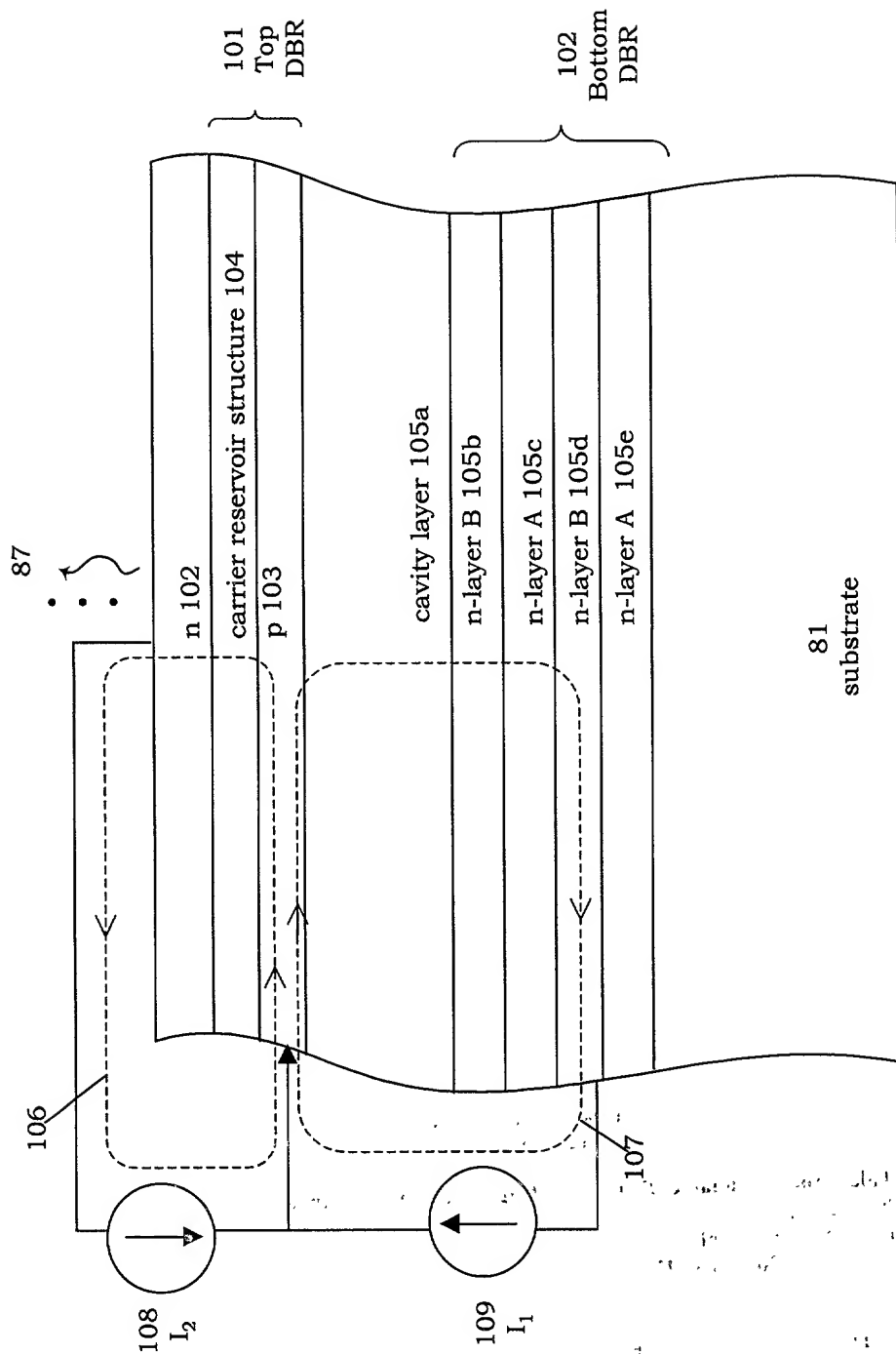


FIG. 7







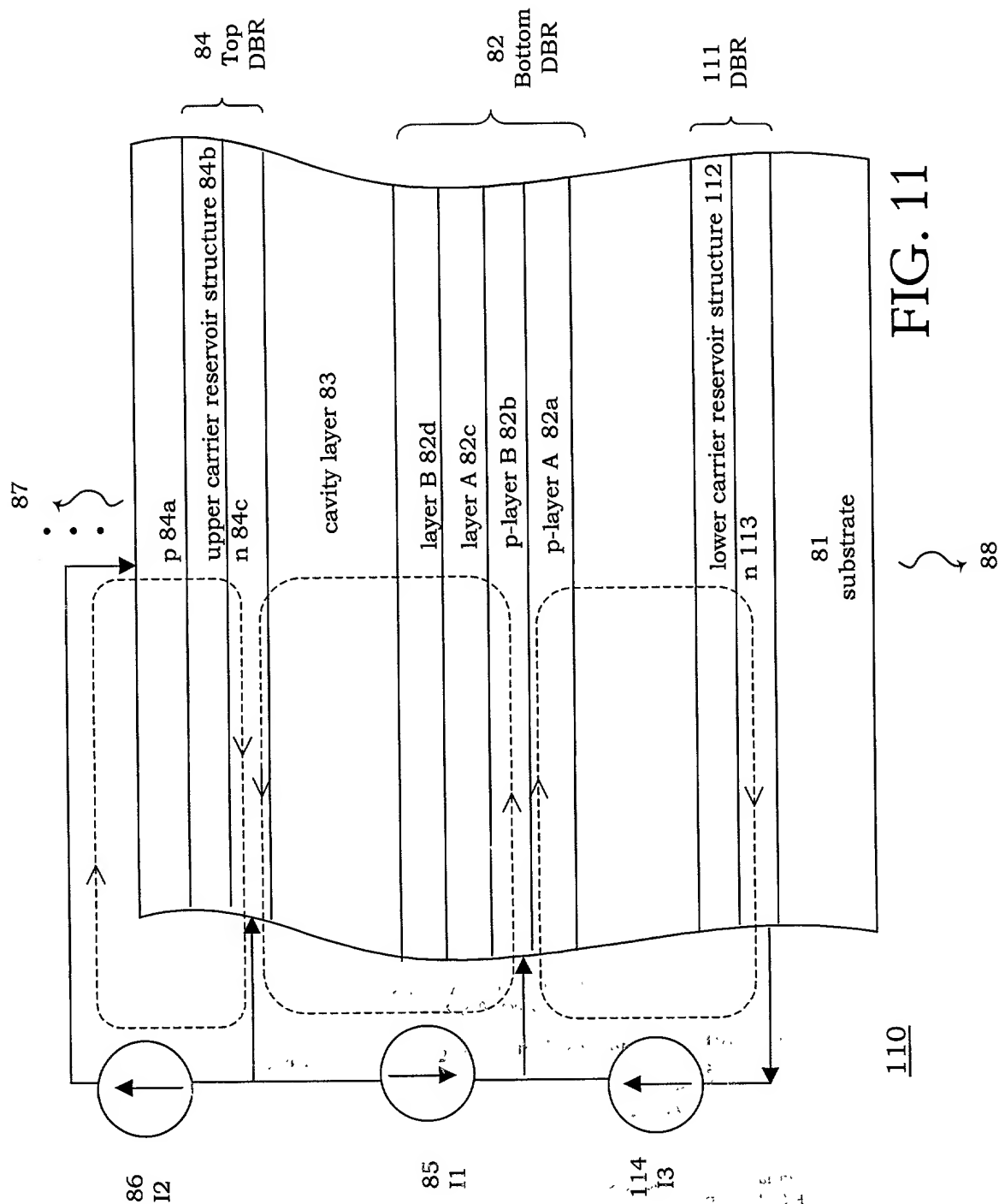
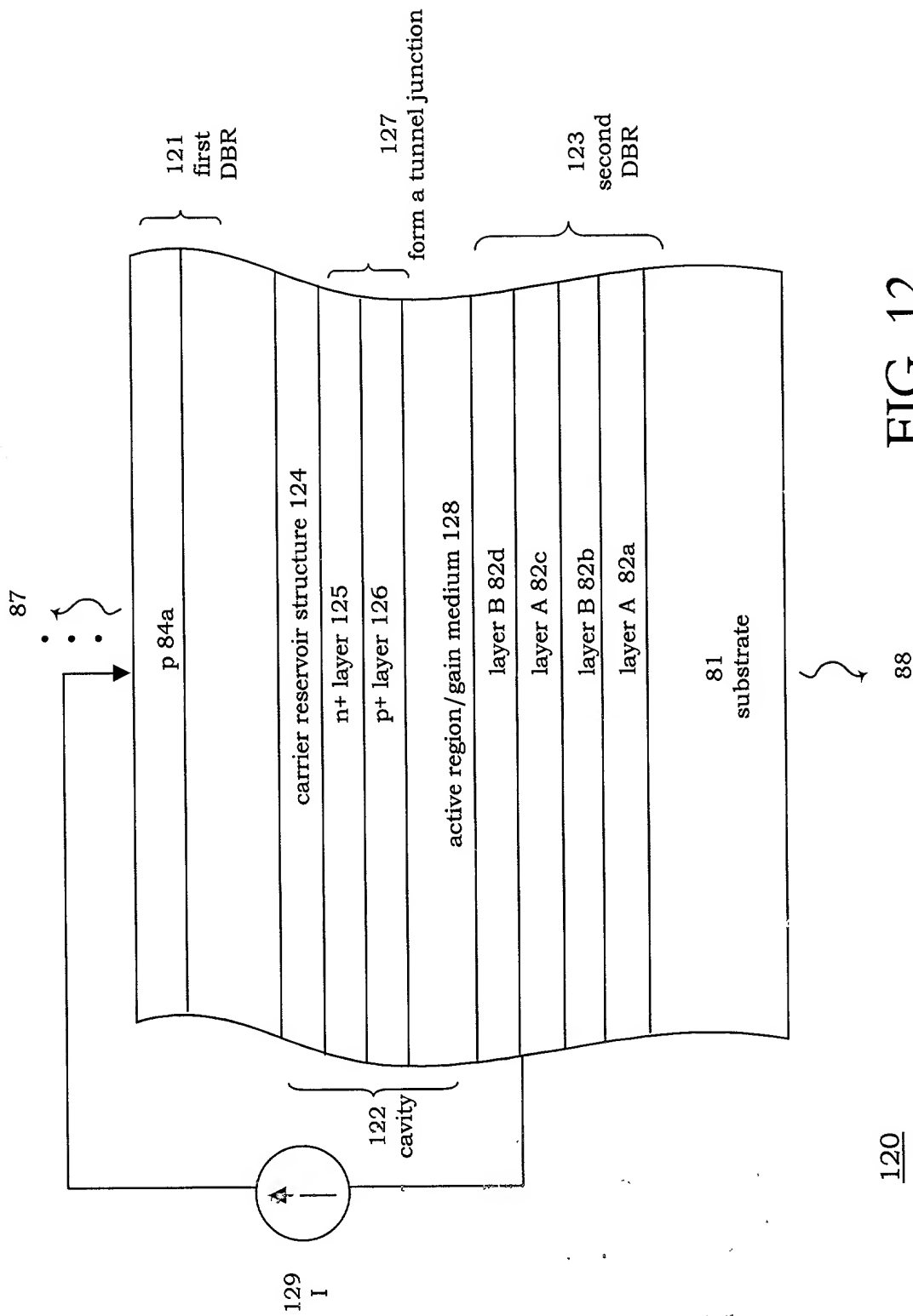
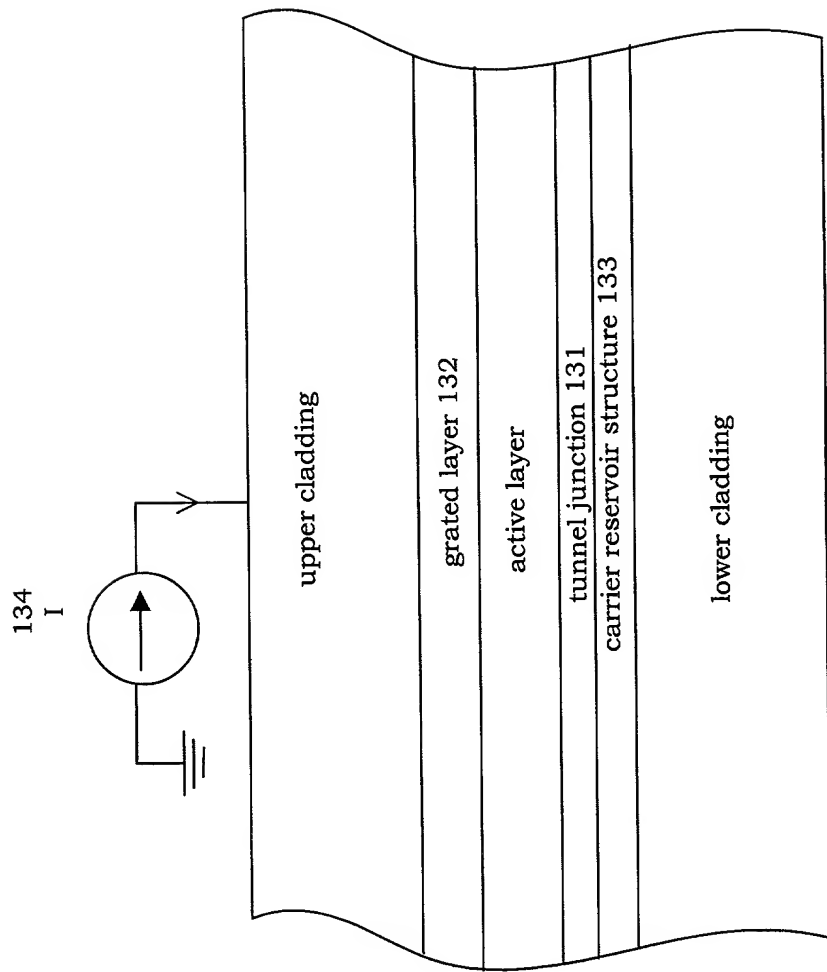


FIG. 11





130

FIG. 13

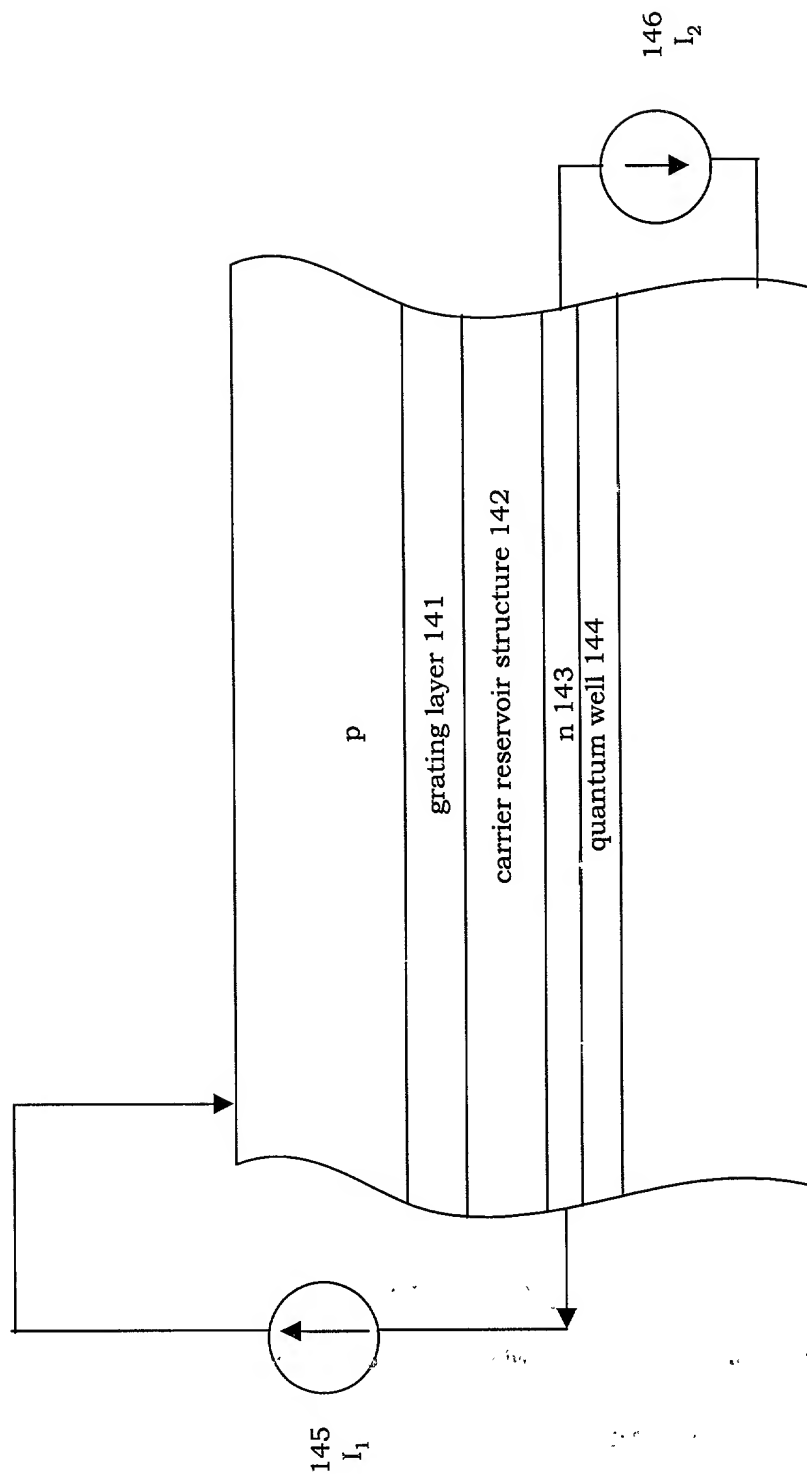


FIG. 14

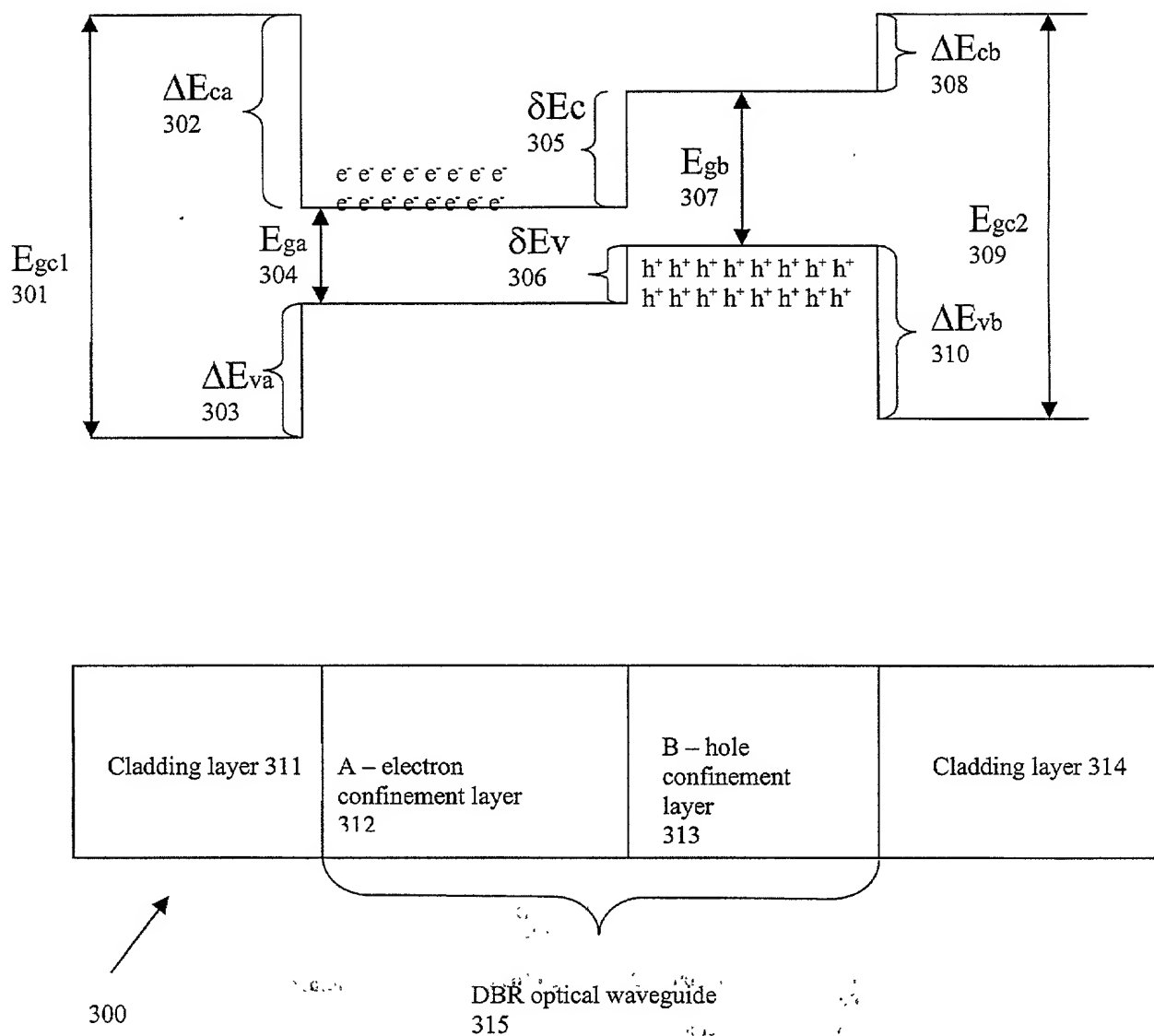
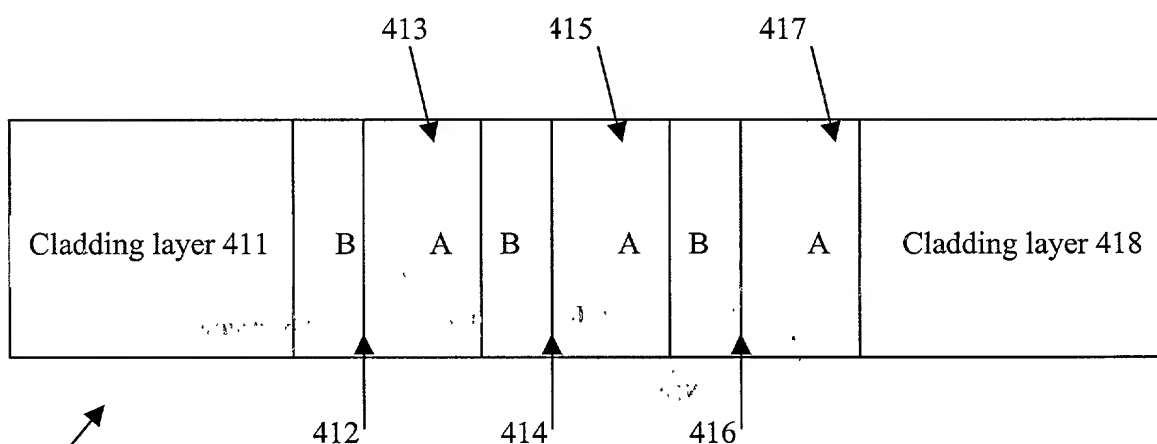
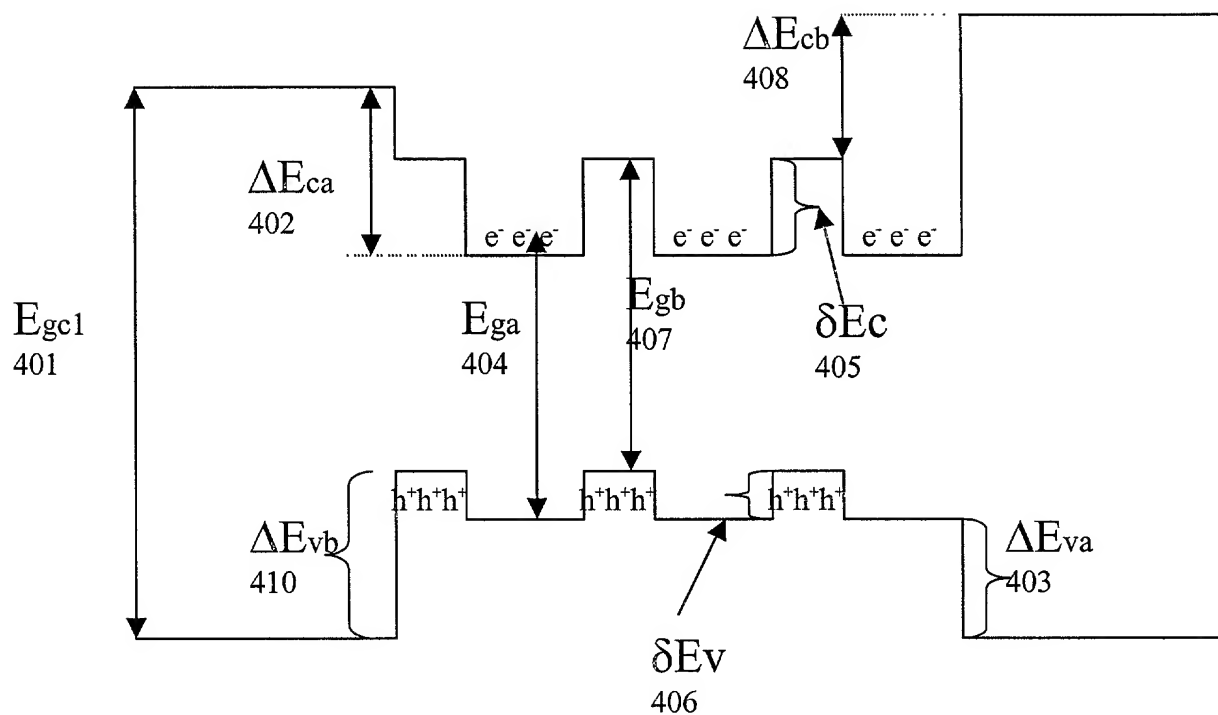


FIG. 15



400

A= electron confinement layer
B= hole confinement layer

FIG.16

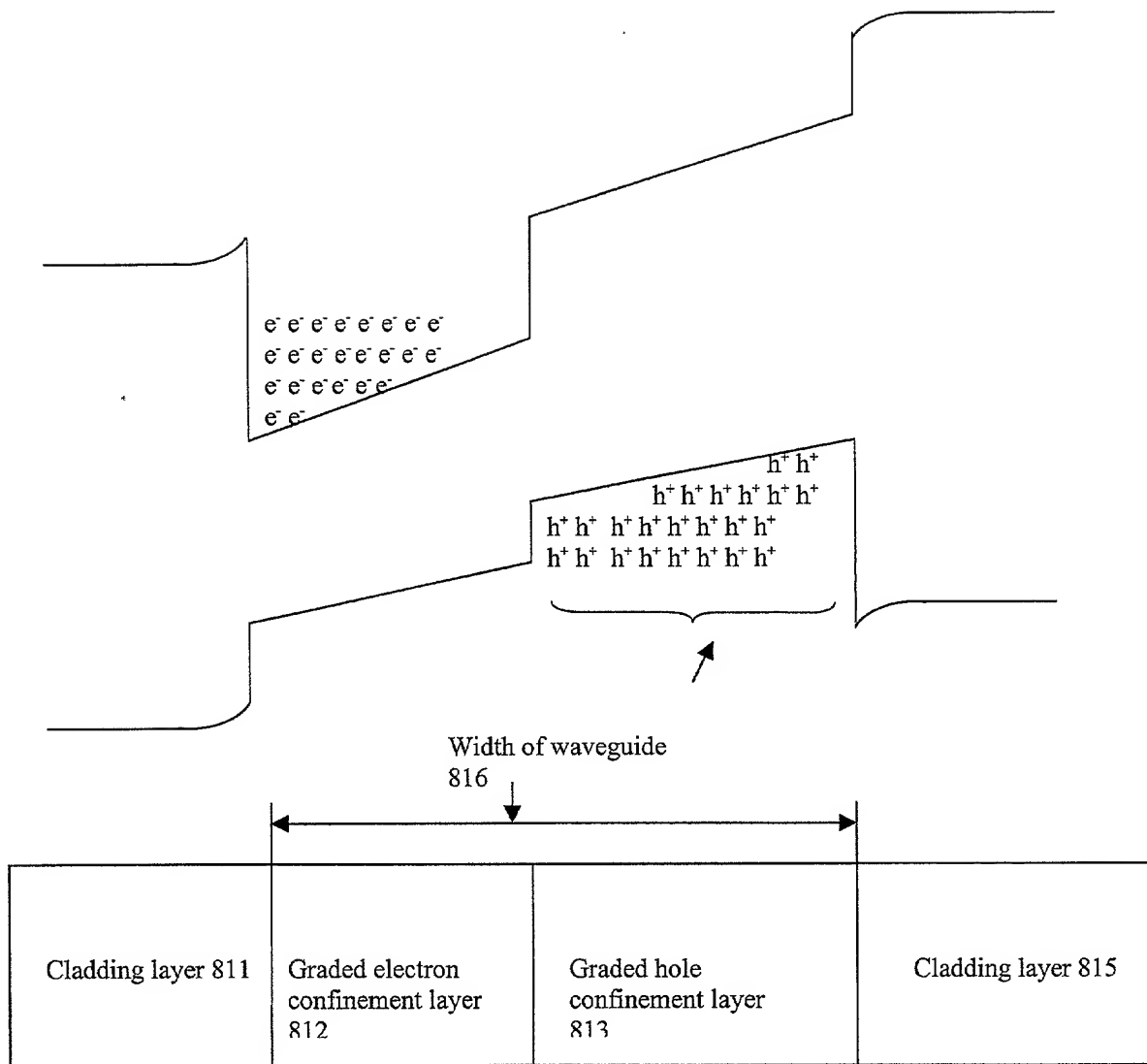


FIG. 17

FIG. 18

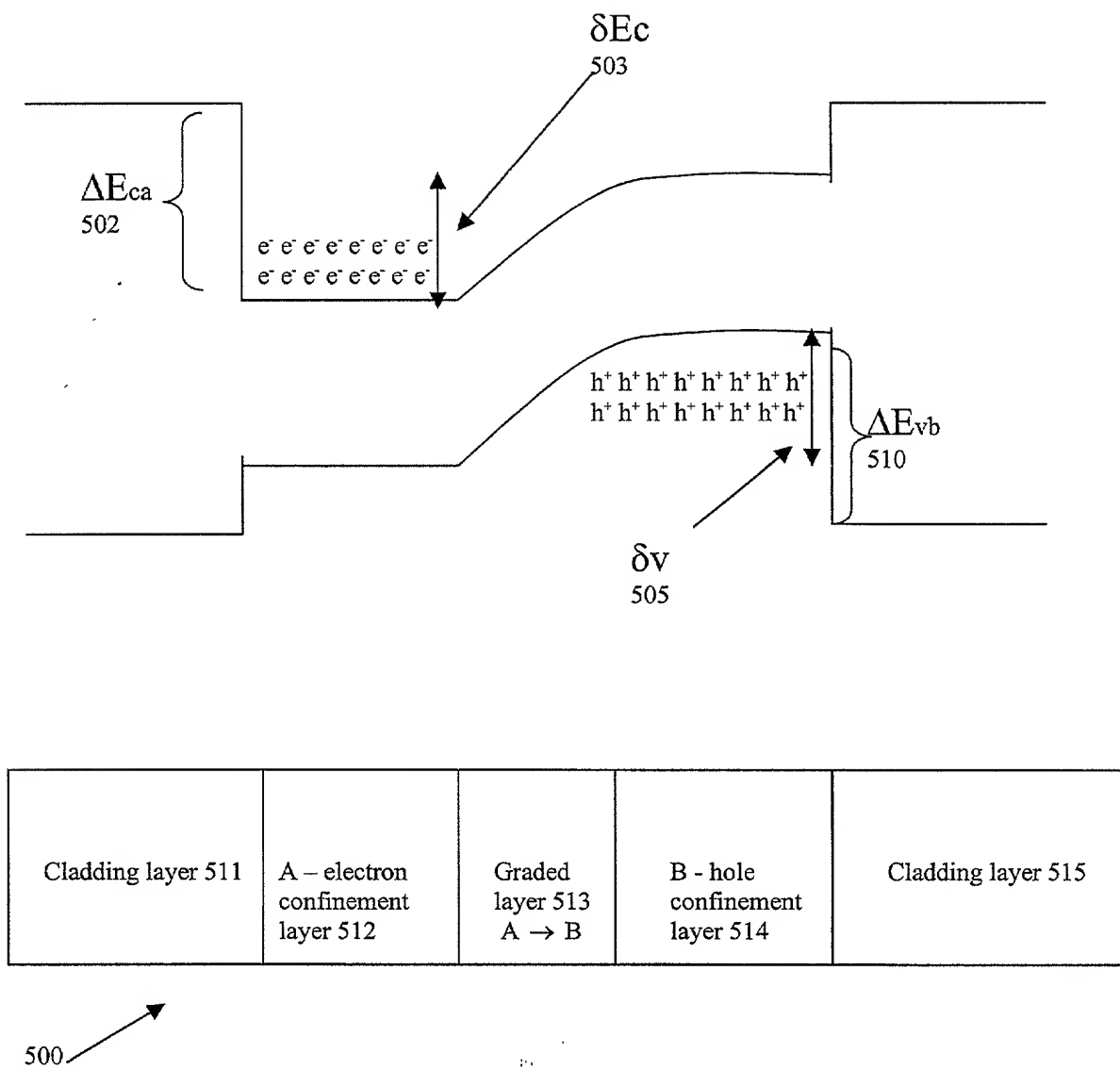


FIG. 18

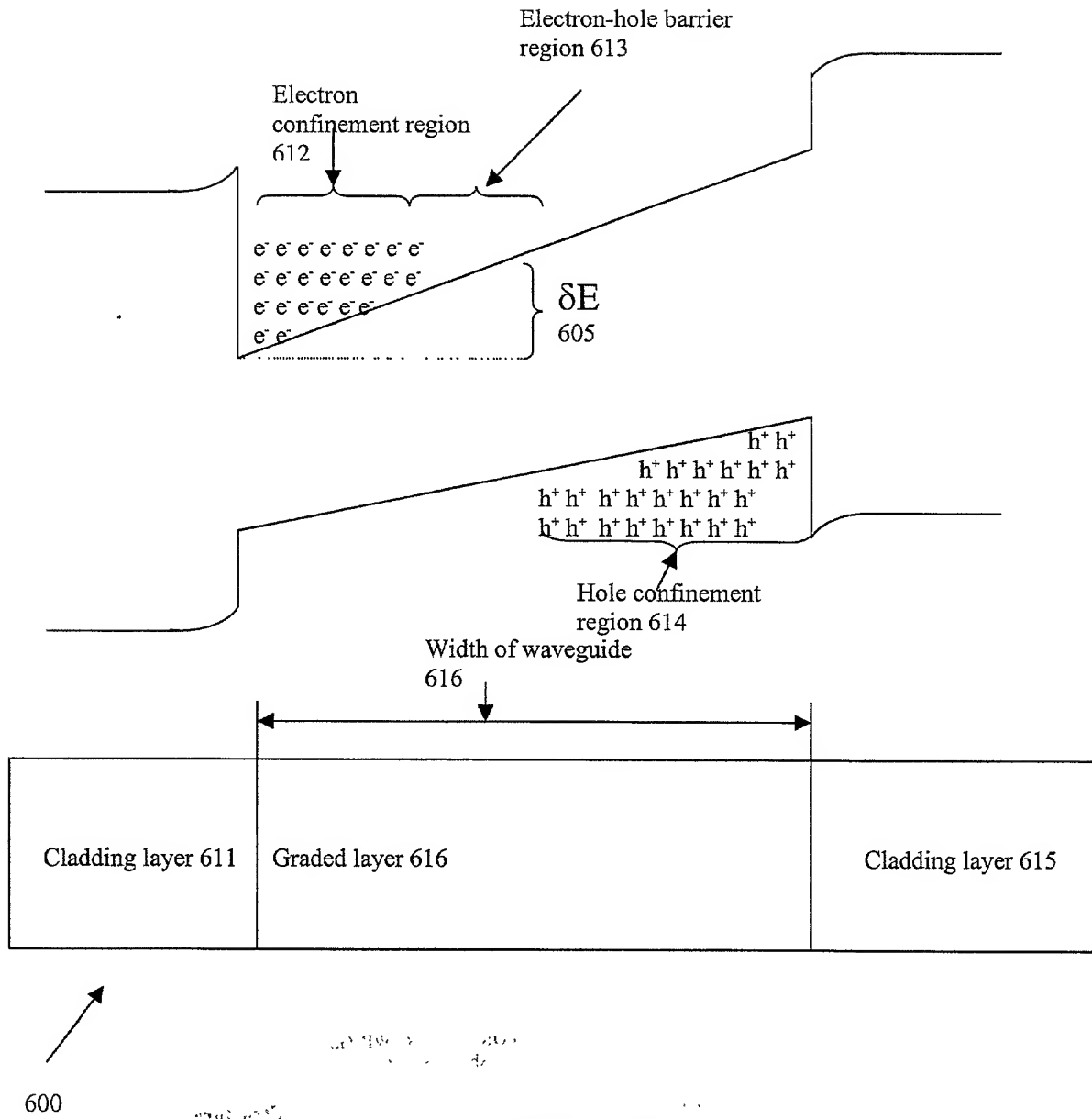


FIG. 19

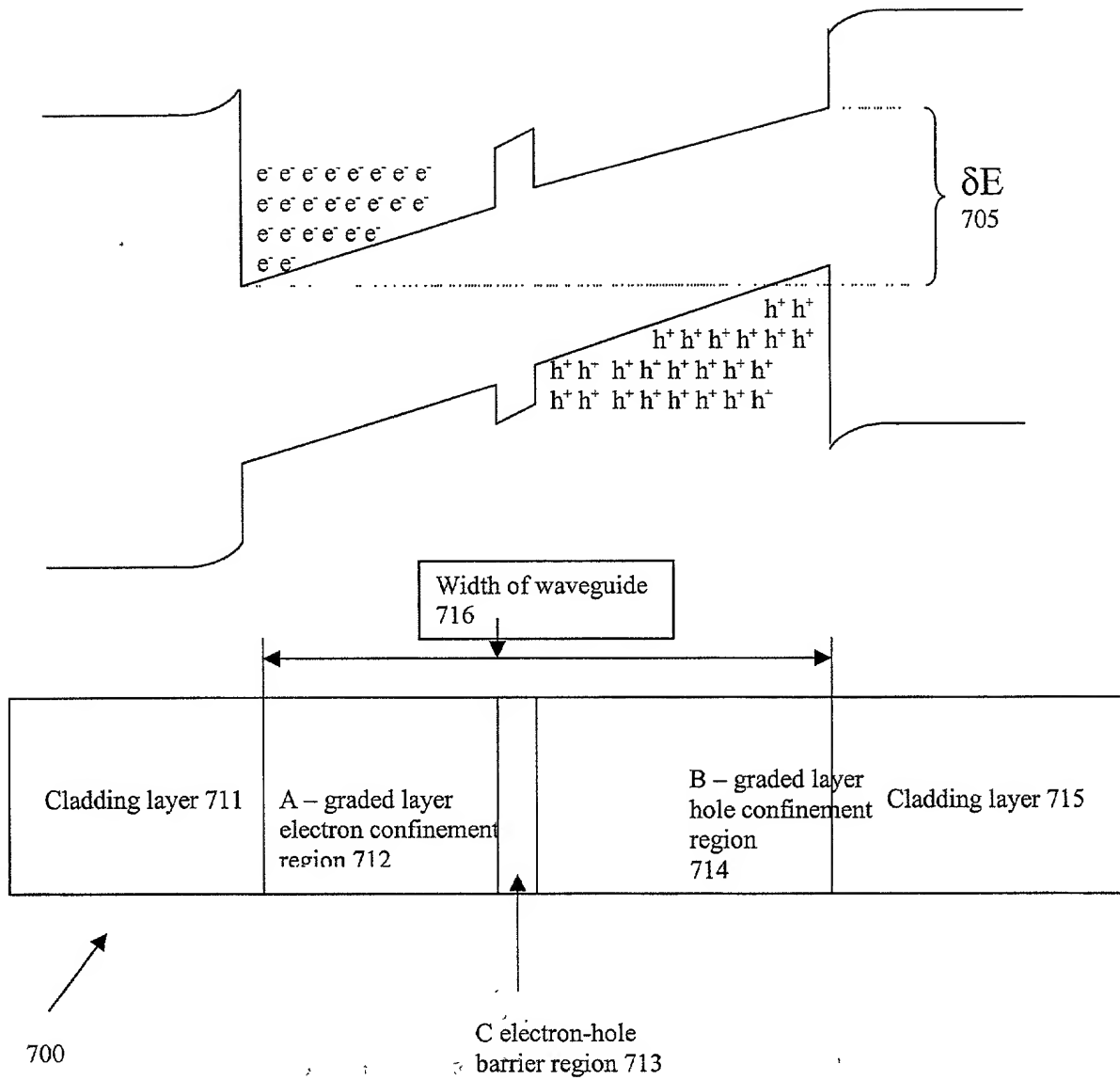


FIG. 20

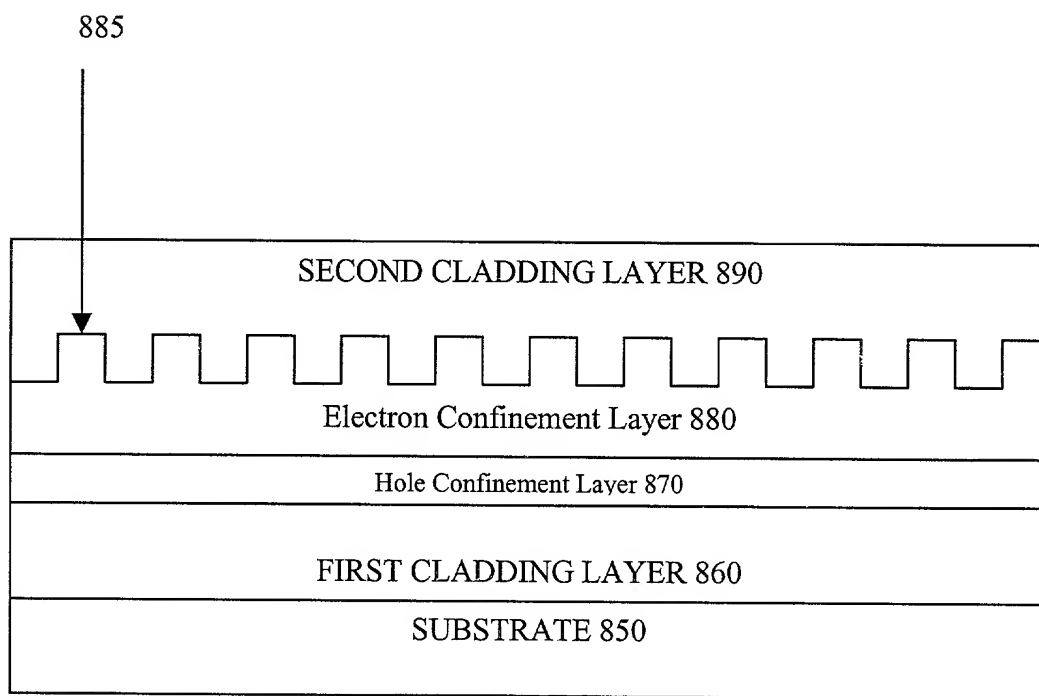


FIG. 21

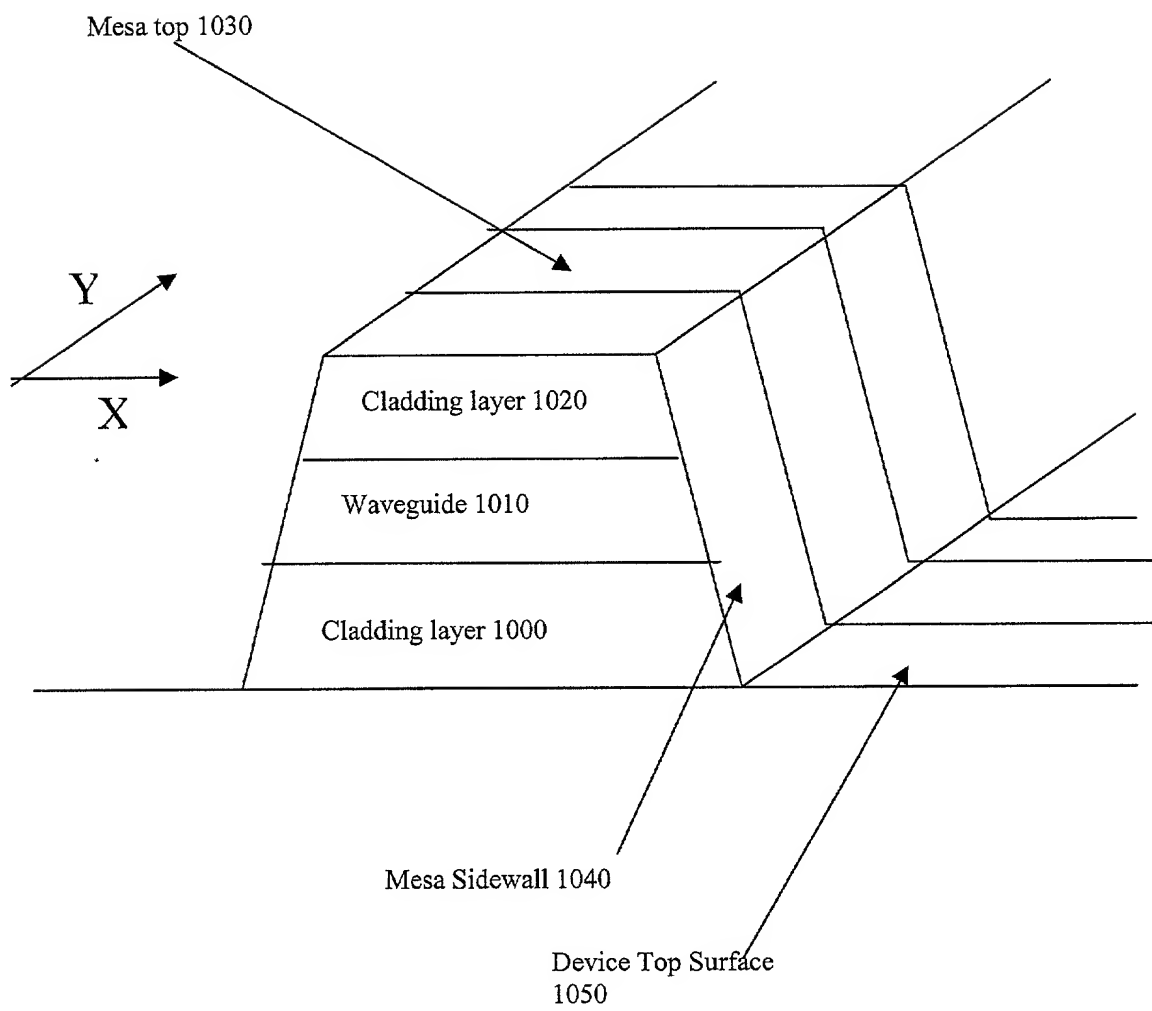
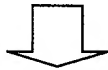


FIG. 22

Create a first cladding layer (Step 910).



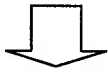
Create a grating layer (Step 920).



Create a hole confinement region layer (Step 930).



Create an electron confinement region layer (Step 940).



Create a second cladding layer (Step 950).



(Optional) Pattern laser structure and additional device processing (Step 960).

FIG. 23